

L Number	Hits	Search Text	DB	Time stamp
-	8	((("5892288") or ("6216937") or ("6287949") or ("6301121"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 16:45
-	9296	(257/779,723,778,747,669,678,737,700,783).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17
-	2896	(438/106,121).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17
-	1926	(multi-chip multi?chip multi adj chip) and mount\$3 near3 board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:08
-	523	((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 16:48
-	235	((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode) and interconnect\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 16:49
-	5	((multi-chip multi?chip multi adj chip) and mount\$3 near3 board) and electrode) and interconnect\$3) and stress near3 relaxat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 04:42
-	2	("6696765").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 04:44
-	0	10/700470	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 04:44
-	39	(multi-chip multi?chip multi adj chip) and stress near3 relaxat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:10
-	9	(multi-chip multi?chip multi adj chip) and ((stress near3 relaxat\$3) with thick\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17
-	9296	(257/779,723,778,747,669,678,737,700,783).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17

-	2896	(438/106,121).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17
-	3	((438/106,121).CCLS.) and ((stress near3 relaxat\$3) with thick\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:17
-	19	((257/779,723,778,747,669,678,737,700,783).CCLS.) and ((stress near3 relaxat\$3) with thick\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:52
-	1		USPAT	2004/03/26 05:45
-	1		USPAT	2004/03/26 05:45
-	1		USPAT	2004/03/26 05:46
-	1		USPAT	2004/03/26 05:46
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-	1		USPAT	2004/03/26 05:46
-	19	"126044"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 05:53

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(3) ((438/106,121) CCLS.) and ((stress near3 relaxat\$3
(19) ((257/779,723,778,747,669,678,737,700,783) CC
(1) "5892288".PN
(1) "6216937".PN
(1) "5669545".PN
(1) "6216937".PN

DBs

USPAT,US-PCPUB,EPO,JPO,DERWENT,IBM,TOB

Plurals

Default operator

OR

Highlight all hit terms initially

((257/779,723,778,747,669,678,737,700,783) CCLS) and ((stress near3 relaxat\$3) with thick\$4)

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	U	1	Document ID	Issue Date	Pages	Title	Current	Cur Re	Inventor	S	C	P	3
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6710446 B2	20040323	20	Semiconductor device co	257/737	257/	Nagai, Akira et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12	<input type="checkbox"/>	<input type="checkbox"/>	US 6696765 B2	20040224	14	Multi-chip module	257/779	257/	Kazama, Atsushi et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
13	<input type="checkbox"/>	<input type="checkbox"/>	US 6696764 B2	20040224	30	Flip chip type semicondu	257/778	257/	Honda, Hirokazu	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
14	<input type="checkbox"/>	<input type="checkbox"/>	US 6624504 B1	20030923	43	Semiconductor device an	257/668	257/	Inoue, Kosuke et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
15	<input type="checkbox"/>	<input type="checkbox"/>	US 6621170 B2	20030916	24	Semiconductor device, s	257/783	156/	Yamamoto, Kazuno	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
16	<input type="checkbox"/>	<input type="checkbox"/>	US 6396145 B1	20020528	21	Semiconductor device an	257/737	228/	Nagai, Akira et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>